Study on Finding Range of Rotation Angle for Effective Transverse Mode Suppression Based on Using Dielectric Stripes Structure of Surface Acoustic Wave Resonators

Fangyi Li^{1†}, Yiwen He¹, Yiming Liu¹, Ying Yang¹, Jingfu Bao^{1*} and Ken-ya Hashimoto¹ (¹Univ. Elect. Sci. Technol. China)

1. Introduction

Resent advance of surface acoustic wave (SAW) technology makes drastic enhancement of device performances such as quality factor (Q). One example is incredible high-performance (I.H.P.) SAW resonators employing very thin 42°YX-LiTaO₃ (42-LT) layer bonded with a Si substrate with a SiO₂ interlayer¹⁻³. Since Q enhancement makes spurious resonances apparent in the resonance characteristics, their suppression is always crucial.

Recently, the authors proposed a new structure for transverse mode suppression⁴). This new design uses dielectric stripes for the piston mode operation of SAW resonators to solve the limit of conventional "hammer-head" design in high MR in double busbar configuration.

This paper discusses applicability of this technique for the I.H.P. configuration with reduced LT rotation angle θ for the enhancement of the electromechanical coupling coefficient (k^2).

2. Variation of k^2 and slowness curve with θ

Fig. 1 shows a unit cell of the device used for the periodic 3D FEM analysis. The double busbar configuration⁵⁾ was applied for SAW energy confinement. Device parameters used for the simulation are taken from Ref. 4. The metallization ratio (MR) is fixed at 0.5 in the following calculation.



Fig. 1 I.H.P. SAW structure with SiO_2 stripes on the edges of IDT aperture.

Fig. 2 shows variation of k^2 in the structure with θ . It is seen k^2 can be increased by reducing θ .

*baojingfu@uestc.edu.cn

However, reduction of θ makes the SAW slowness curve more convex as shown in **Fig. 3**, and it makes suppression of transverse modes more difficult as long as the "hammer-head" is employed⁶). Note that the slowness curve can be flattened by setting MR small (0.35) as also shown in Fig. 3. The authors demonstrated good transverse mode suppression by the conventional "hammer-head" for I.H.P. SAW structure on 42-LT. In the case, MR is set at 0.35⁷).





Fig. 4(a) shows variation of calculated admittance Y and conductance G of I.H.P. SAW configuration shown in Fig. 1 structure with θ when the SiO₂ stripes are not given. Series of resonance peaks are seen above the resonance frequency. They are due to the transverse mode when the slowness

[†]202222021501@std.uestc.edu.cn,

curve is convex. A low Q peak is seen slightly above the anti-resonance frequency. This is due to the "gap mode" caused by the secondary gap in the double busbar structure⁷.



(b) With SiO₂ stripes.

Fig. 4 Calculated *Y* and *G* of I.H.P. SAW with the double busbar configuration when $\theta = 40^{\circ} - 34^{\circ}$.

Fig. 4(b) shows variation of calculated *Y* and *G* with θ when the SiO₂ stripes are given. Note that SiO₂ height, stripe width and length were adjusted for each θ to offer good transverse mode suppression. It is seen that transverse mode resonances are well suppressed under appropriate settings even when θ is small.

Fig. 5 shows the results when θ is further reduced. Although transverse mode resonances are suppressed in some extent for these cases, they still remain. Furthermore, energy leakage may occur near the main resonance.

4. Conclusion

This paper discussed transverse suppression in the I.H.P. SAW structure with small θ using dielectric stripes.

Excellent transverse mode suppression was realized for θ larger than 34° even when MR=0.5.

When θ is smaller than 34°, some transverse mode resonances remained and energy leakage occurred.



Fig. 5 Calculated *Y* and *G* of I.H.P. SAW with the double busbar configuration when $\theta = 32^{\circ} - 24^{\circ}$.

Acknowledgment

This work was supported in part by the Research Project under Grant A1098531023601318 and in part by the National Natural Science Foundation of China and the China Academy of Engineering Physics under Grant U1430102.

References

- 1) T. Takai, et al., Proc. IEEE Ultrason. Symp. (2016) 10.1109/ULTSYM.2016.7728455.
- T. Takai, et al., Tech. Digest, IEEE MTT-S IMS (2016) 10.1109/MWSYM.2016.7540214.
- 3) T. Takai, et al., IEEE Trans. UFFC, **64** (2017) pp. 1382-1389.
- 4) F. Li, et al., Proc. IEEE MTT-S IC-MAM (2024) pp. 161-164.
- 5) Y. He, et al., IEEE Trans. UFFC, **69** (2022) pp. 1112-1119.
- 6) Y. He, et al., IEEE Trans. UFFC, **70** (2023) pp. 1246-1251.
- 7) Y.W. He, et al., IEEE Trans. MTT, **71** (2023) pp. 3493-3500.